504385833 05/26/2017

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 EPAS ID: PAT4432529

Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KUNIHIRO SENDA	08/28/2014
HIROTAKA INOUE	08/28/2014
SEIJI OKABE	08/28/2014

RECEIVING PARTY DATA

Name:	JFE STEEL CORPORATION	
Street Address:	2-3, UCHISAIWAI-CHO 2-CHOME	
Internal Address:	CHIYODA-KU	
City:	TOKYO	
State/Country:	JAPAN	
Postal Code:	100-0011	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15606074

CORRESPONDENCE DATA

Fax Number: (215)656-2498

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 215-656-3381

Email: pto.phil@dlapiper.com

Correspondent Name: IP GROUP OF DLA PIPER LLP (US)

Address Line 1: ONE LIBERTY PLACE

Address Line 2: 1650 MARKET ST, SUITE 4900

Address Line 4: PHILADELPHIA, PENNSYLVANIA 19103

ATTORNEY DOCKET NUMBER:	SUG-14-2056DIV/308880-081	
NAME OF SUBMITTER:	LESLIE J. HOOD	
SIGNATURE:	/LJH/	
DATE SIGNED:	05/26/2017	

Total Attachments: 1

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PATENT REEL: 042513 FRAME: 0993

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WHEREAS, wc, Kunihiro Scnda, Hirotaka Inoue, and Seiji Okabe, all citizens of Japan, all residing at c/o Intellectual Property Dept., JFE Steel Corporation, 2-3, Uchisaiwai-cho 2-chome, Chiyoda-ku, Tokyo, 1000011 Japan, (hereinafter referred to as "the undersigned"), having made an invention entitled GRAIN-ORIENTED ELECTRICAL STEEL SHEET AND METHOD FOR MANUFACTURING SAME, identified in International Application No. PCT/JP2012/002875, and in US Application No. 14/395, 900 (DLA Piper is authorized to insert the Serial No. when known).

WHEREAS, JFE Steel Corporation, with offices located at 2-3, Uchisaiwai-cho 2-chome, Chiyoda-ku, Tokyo, 1000011 Japan (hereinafter referred to as "the assignee"), is desirous of acquiring the entire right, title and interest in said invention, said US application and all letters patent issuing for said invention,

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and of other good and valuable consideration, receipt of which is hereby acknowledged, the undersigned, intending to be legally bound, do hereby sell, assign and transfer to the assignee the entire right, title and interest, for the United States of America, its territories and possessions, and for all foreign countries, in said invention, including said US application, all divisions and continuations thereof, all rights to claim priority based thereon, all rights to file foreign applications on said invention, and all letters patent and reissues thereof, issuing for said invention in the United States of America and in any and all foreign countries.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the undersigned has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the assignee, and to execute all instruments proper to carry out the intent of this instrument. If the undersigned includes more than one individual, these obligations shall apply to all of the undersigned both individually and collectively.

The rights and property herein conveyed by the undersigned are free and clear of any encumbrance.

EXECUTED on the date(s) set forth below.

August 28, 2014

August 28, 2014

August 28, 2014

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